

### MOS FIELD EFFECT TRANSISTOR

**2SJ607** 

## SWITCHING P-CHANNEL POWER MOS FET INDUSTRIAL USE

#### **DESCRIPTION**

The 2SJ607 is P-channel MOS Field Effect Transistor designed for high current switching applications.

#### **FEATURES**

- Super low on-state resistance:
  - $R_{DS(on)1}=11~m\Omega~MAX.~(V_{GS}=-10~V,~I_{D}=-42~A)$   $R_{DS(on)2}=16~m\Omega~MAX.~(V_{GS}=-4.0~V,~I_{D}=-42~A)$
- Low Ciss: Ciss = 7500 pF TYP.
- Built-in gate protection diode

#### **ORDERING INFORMATION**

| PART NUMBER | PACKAGE                   |
|-------------|---------------------------|
| FART NUMBER | FACRAGE                   |
| 2SJ607      | TO-220AB                  |
| 2SJ607-S    | TO-262                    |
| 2SJ607-ZJ   | TO-263                    |
| 2SJ607-Z    | TO-220SMD <sup>Note</sup> |

**Note** TO-220SMD package is produced only in Japan.

#### ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

| Drain to Source Voltage (V <sub>GS</sub> = 0 V) | VDSS             | -60         | V  |
|---|------------------|-------------|----|
| Gate to Source Voltage (V <sub>DS</sub> = 0 V)  | Vgss             | ∓ 20        | V  |
| Drain Current (DC) (Tc = 25°C)                  | ID(DC)           | ∓ 83        | Α  |
| Drain Current (pulse) Note1                     | D(pulse)         | ∓ 332       | Α  |
| Total Power Dissipation (Tc = 25°C)             | PT               | 160         | W  |
| Total Power Dissipation (T <sub>A</sub> = 25°C) | PT               | 1.5         | W  |
| Channel Temperature                             | Tch              | 150         | °C |
| Storage Temperature                             | T <sub>stg</sub> | -55 to +150 | °C |
| Single Avalanche Current Note2                  | las              | -50         | Α  |
| Single Avalanche Energy Note2                   | Eas              | 250         | mJ |

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1%

2. Starting T<sub>ch</sub> = 25°C, R<sub>G</sub> = 25  $\Omega$ , V<sub>GS</sub> = -20 V  $\rightarrow$  0 V

(TO-220AB)



(TO-262)



(TO-263, TO-220SMD)



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Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

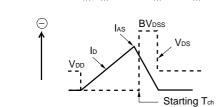


#### **ELECTRICAL CHARACTERISTICS (TA = 25°C)**

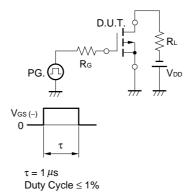
| OLIA DA OTEDIOTICO                  | 0)/44001             | TEST SOMBITIONS  |      | T) (D | B 4 6 3 / |      |
|-------------------------------------|----------------------|--|------|-------|-----------|------|
| CHARACTERISTICS                     | SYMBOL               | TEST CONDITIONS  | MIN. | TYP.  | MAX.      | UNIT |
| Zero Gate Voltage Drain Current     | loss                 | V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V                             |      |       | -10       | μΑ   |
| Gate Leakage Current                | lgss                 | $V_{GS} = \mp 20  \text{V},  V_{DS} = 0  \text{V}$                         |      |       | ∓ 10      | μΑ   |
| Gate Cut-off Voltage                | V <sub>GS(off)</sub> | $V_{DS} = -10  V,  I_{D} = -1  mA$   | 1.5  | 2.0   | 2.5       | V    |
| Forward Transfer Admittance         | yfs                  | $V_{DS} = -10 \text{ V}, \text{ ID} = -42 \text{ A}$                       | 45   | 90    |           | S    |
| Drain to Source On-state Resistance | RDS(on)1             | V <sub>GS</sub> = -10 V, I <sub>D</sub> = -42 A                            |      | 9.1   | 11        | mΩ   |
|                                     | RDS(on)2             | V <sub>G</sub> S = -4.0 V, I <sub>D</sub> = -42 A                          |      | 11    | 16        | mΩ   |
| Input Capacitance                   | Ciss                 | V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V, f = 1 MHz                  |      | 7500  |           | pF   |
| Output Capacitance                  | Coss                 |  |      | 1800  |           | pF   |
| Reverse Transfer Capacitance        | Crss                 |  |      | 430   |           | pF   |
| Turn-on Delay Time                  | td(on)               | $I_D = -42 \text{ A}, V_{GS(on)} = -10 \text{ V}, V_{DD} = -30 \text{ V},$ |      | 23    |           | ns   |
| Rise Time                           | tr                   | $R_G = 0 \Omega$   |      | 16    |           | ns   |
| Turn-off Delay Time                 | t <sub>d(off)</sub>  |  |      | 340   |           | ns   |
| Fall Time                           | t <sub>f</sub>       |  |      | 160   |           | ns   |
| Total Gate Charge                   | Q <sub>G</sub>       | ID = -83 A, VDD= -48 V, VGS = -10 V  |      | 188   |           | nC   |
| Gate to Source Charge               | Qgs                  |  |      | 30    |           | nC   |
| Gate to Drain Charge                | Q <sub>GD</sub>      |  |      | 48    |           | nC   |
| Body Diode Forward Voltage          | V <sub>F</sub> (S-D) | IF = -83 A, VGS = 0 V  |      | 1.0   |           | V    |
| Reverse Recovery Time               | trr                  | IF = -83 A, VGS = 0 V  |      | 64    |           | ns   |
| Reverse Recovery Charge             | Qrr                  | $di/dt = -100 \text{ A}/\mu\text{s}$                                       |      | 150   |           | nC   |

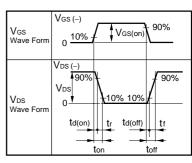
#### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c} \text{D.U.T.} \\ \text{Rg} = 25 \ \Omega \\ \text{V} \\ \text{V} \\ \text{SO} \end{array}$

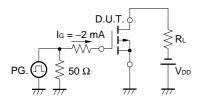


#### TEST CIRCUIT 2 SWITCHING TIME





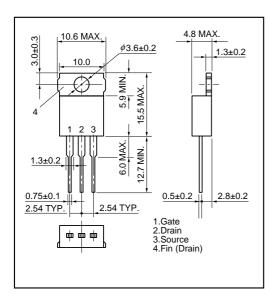
#### **TEST CIRCUIT 3 GATE CHARGE**



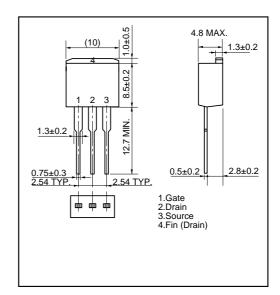


#### PACKAGE DRAWINGS (Unit: mm)

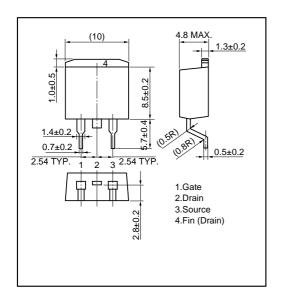
#### 1) TO-220AB(MP-25)



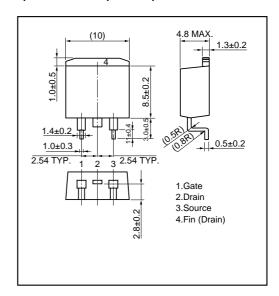
#### 2) TO-262(MP-25 Fin Cut)



#### 3) TO-263 (MP-25ZJ)

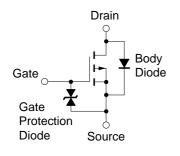


#### 4) TO-220SMD(MP-25Z)<sup>Note</sup>



Note This Package is produced only in Japan.

#### **EQUIVALENT CIRCUIT**



Remark

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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